

GENERAL DESCRIPTION

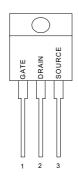
This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

FEATURES

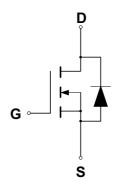
- Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- ◆ I_{DSS} Specified at Elevated Temperature

PIN CONFIGURATION

TO-220/TO-220FP Front View



SYMBOL



N-Channel MOSFET



ABSOLUTE MAXIMUM RATINGS

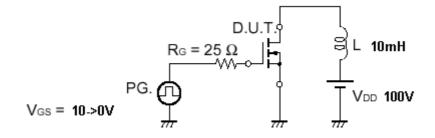
Rating S	ymbol	Value	Unit
Drain to Current — C ontinuous	I _D	6.0	Α
− Pu lsed	I _{DM}	18	
Gate-to-Source Voltage — C ontinue	V_{GS}	±20	V
N on-repetitive	V _{GSM}	±40	V
Total Power Dissipation	P _D		W
T O-220		125	
TO-220FP		45	
Operating and Storage Temperature Range	T _J , T _{STG} -5	5 to 150	°C
Single Pulse Drain-to-Source Avalanche Energy $-$ T $_{\! extsf{J}}$ = $25^\circ\!\!$ C			mJ
$(V_{DD} = 100V, V_{GS} = 10V, I_L = 6A, L = 10mH, R_G = 25\Omega)$	E _{AS}	180	
Thermal Resistance — Junction to Case	θ _{JC}	1.0	°C/W
 Junction to Ambient 	θЈΑ	62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T _L 260		°C

- (1) VDD = 50V, ID = 6A
- (2) Pulse Width and frequency is limited by T_{J(max)} and thermal response

ORDERING INFORMATION

Part Number	Package		
IRF6N60	TO-220		
IRF6N60FP	TO-220 Full Pak		

TEST CIRCUIT



Test Circuit - Avalanche Capability



ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^{\circ}C$.

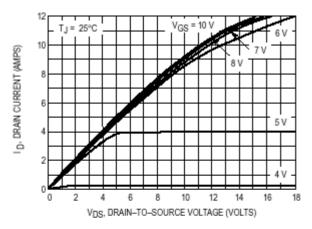
			IRF6N60			
Cha	racteristic	Symbol	Min	Тур	Max	Units
Drain-Source Breakdown Voltage	V _{(BR)DSS} 600				V	
$(V_{GS} = 0 \text{ V}, I_D = 250 \ \mu \text{ A})$						
Drain-Source Leakage Current	, == , ,					μA
$(V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V})$				100		
$(V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125^{\circ}\text{C}$				50		
Gate-Source Leakage Current-Forwa	I _{GSSF}			100	nA	
$(V_{gsf} = 20 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate-Source Leakage Current-Rever	Gate-Source Leakage Current-Reverse				100	nA
$(V_{gsr} = 20 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate Threshold Voltage		V _{GS(th)} 2.	0		4.0	V
$(V_{DS} = V_{GS}, I_D = 250 \mu A)$						
Static Drain-Source On-Resistance (\	R _{DS(on)}			1.2	Ω	
Forward Transconductance (V _{DS} = 15	g _{FS} 3.	4			mhos	
Input Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}.$	C _{iss}		1498	2100	pF
Output Capacitance	$(v_{DS} - 25 \text{ v}, v_{GS} - 0 \text{ v},$ f = 1.0 MHz)	C _{oss}		158	220	pF
Reverse Transfer Capacitance	1 – 1.0 Wil 12)	C _{rss}		29	60	pF
Turn-On Delay Time	// - 200 \/ I - 0 0 A	t _{d(on)}		14	30	ns
Rise Time	$(V_{DD} = 300 \text{ V}, I_D = 6.0 \text{ A}, V_{GS} = 10 \text{ V}.$	t _r		19	40	ns
Turn-Off Delay Time	$V_{GS} = 10 \text{ V},$ $R_{G} = 9.1\Omega) *$	t _{d(off)}		40	80	ns
Fall Time	$N_G = 9.1\Omega$)	t _f		26	55	ns
Total Gate Charge	0/ 000 // 1 00 0	Q_g		35.5	50	nC
Gate-Source Charge	$(V_{DS} = 300 \text{ V}, I_D = 6.0 \text{ A}, V_{GS} = 10 \text{ V})^*$	Q_{gs}		8.1		nC
Gate-Drain Charge	V _{GS} = 10 V)"	Q_{gd}	14.	1		nC
Internal Drain Inductance	L _D		4.5		nH	
(Measured from the drain lead 0.25	" from package to center of die)					
Internal Drain Inductance	Ls		7.5		nH	
(Measured from the source lead 0.3	25" from package to source bond pad)					
SOURCE-DRAIN DIODE CHARACT	ERISTICS					
Forward On-Voltage(1)	// - C O A	V _{SD}		0.83	1.2	V
Forward Turn-On Time	$(I_S = 6.0 \text{ A}, d_{IS}/d_t = 100\text{A/}\mu\text{s})$	t _{on}		**		ns
Reverse Recovery Time	t _{rr}		266		ns	

^{*} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%

^{**} Negligible, Dominated by circuit inductance



TYPICAL ELECTRICAL CHARACTERISTICS



V_{DS} ≥ 10 V

8

10

4

2

100°C

25°C

T_J = -55°C

0

2.0

25

3.0

3.5

4.0

4.5

5.0

5.5

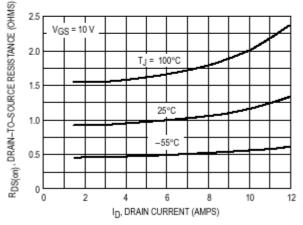
6.0

V_{GS}, GATE-TO-SOURCE VOLTAGE (VOLTS)

12

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



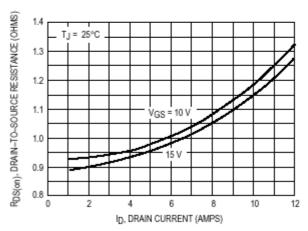
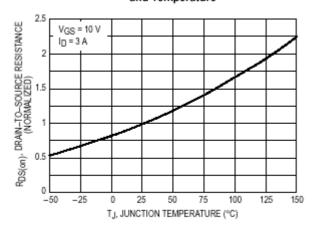


Figure 3. On–Resistance versus Drain Current and Temperature

Figure 4. On–Resistance versus Drain Current and Gate Voltage



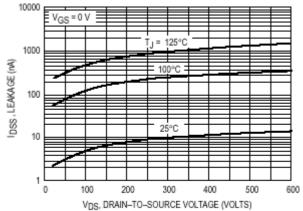
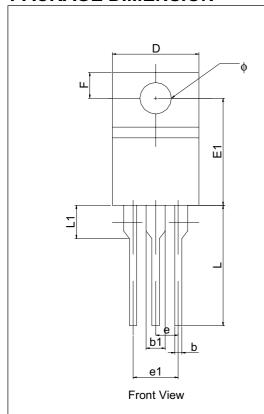


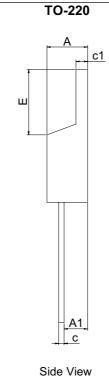
Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-To-Source Leakage Current versus Voltage



PACKAGE DIMENSION

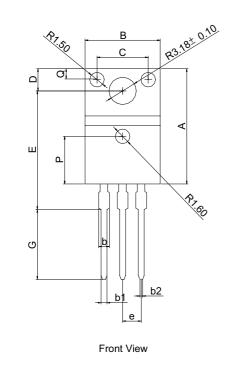


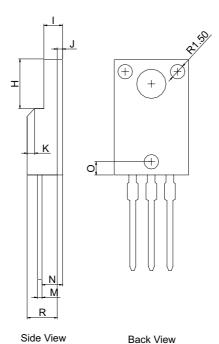


PIN 1: GATE PIN 2: DRAIN PIN 3: SOURCE

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHS			
SIMBOLS	MIN	NOM	MAX	MIN	NOM	MAX	
Α	4.47		4.67	0.176		0.184	
A1	2.52		2.82	0.099		0.111	
b	0.71		0.91	0.028		0.036	
b1	1.17		1.37	0.046		0.054	
С	0.31		0.53	0.012		0.021	
c1	1.17		1.37	0.046		0.054	
D	10.01		10.31	0.394		0.406	
E	8.50		8.90	0.335		0.350	
E1	12.06		12.46	0.475		0.491	
е		2.54			0.100		
e1	4.98		5.18	0.196		0.204	
F	2.59		2.89	0.102		0.114	
L	13.40		13.80	0.528		0.543	
L1	3.56		3.96	0.140		0.156	
ф	3.79		3.89	0.149		0.153	

TO-220FP





an mar a	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHS		
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
A	15.67		16.07	0.617		0.633
В	9.96		10.36	0.392		0.408
С		7.00			0.275	
D	3.20		3.40	0.126		0.134
Е	15.60		16.00	0.614		0.630
G	9.45		10.05	0.372		0.396
Н	6.48		6.88	0.255		0.279
- 1	2.34		2.74	0.092		0.108
L		0.70			0.028	
ĸ		1.00			0.039	
М	0.45		0.60	0.018		0.024
N	2.56		2.96	0.101		0.117
0		1.80			0.071	
Р		6.50			0.256	
Q		1.50			0.059	
R	4.50		4.90	0.177		0.193
b			1.47			0.058
b1	0.70		0.90	0.028		0.035
b2	0.25		0.45	0.010		0.018
е		2.54			0.100	